

2014 IEEE

International Symposium
on Electromagnetic
Compatibility

CALL FOR PAPERS

2014 IEEE International Conference on Signal and Power Integrity (SIPI-2014)

an embedded conference within the
2014 IEEE International Symposium on Electromagnetic Compatibility
Dates: 4 - 8 August 2014

Location: Raleigh Convention Center, Raleigh, NC, USA

Information for Authors

The 2014 IEEE International Conference on Signal and Power Integrity (SIPI 2014) will be held as an embedded conference within the 2014 IEEE International Symposium on Electromagnetic Compatibility the week of August 4 - 8, 2014. Registered attendees will have access to the entire EMC Symposium program, in addition to the programs of SIPI 2014, without additional fees. As high-speed designs continue to evolve, signal/power integrity and other EMC problems are becoming more tightly related. This conference provides a unique opportunity for attendees to exchange ideas and share experiences relevant to today's high-speed designs.

Join your colleagues and experts/innovators in Raleigh, NC for a full week of technical presentations on advances and research in EMC, SI, PI and other related fields. Conference proceedings will be submitted for posting to IEEE Xplore. In addition, authors of accepted papers will be invited to submit an extended version of their symposium paper for possible publication in a special issue of the IEEE Transactions on Electromagnetic Compatibility. Proposals for special sessions, workshops, tutorials, and experiments are also encouraged.

Interconnects

- High-speed interconnect design and optimization (component and/or system level)
- Interconnect modeling and extraction
- Channel analysis

Power Distribution Network and Decoupling

- PDN (power delivery network) design and optimization
- Design, analysis, simulation, modeling measurement techniques

Chip level

- On-chip and off-chip high-speed signaling techniques
- 3-D IC and TSV

Paper Topics of Interest

Topics include and are not limited to the following technical areas (sample topics shown).

Tools and methodologies

- Jitter/Noise/Crosstalk/BER budgeting, analysis, and measurement
- De-embedding method
- Time domain and frequency domain measurement techniques

Simulation and modeling techniques

- High-frequency and electromagnetic simulation techniques
- Simulation and measurement correlation
- Advanced simulation tools/algorithms
- Device modeling and characterization

System co-design

- Signal/power integrity for chip/package/board/connector/cable design
- Signal integrity and power integrity co-analysis
- System-level SI/PI/EMI co-design

Others

- RF, microwave and mixed signal analysis

2014 IEEE

International Symposium
on Electromagnetic
Compatibility



Author Submission Schedule

- **Full Paper Manuscript:** November 1, 2013 - January 20, 2014 (late papers will not be accepted)
- **Acceptance Notification:** March 10, 2014
- **Final Paper and Workshop/Tutorial Material Due:** May 9, 2014

Paper Formats

- **Traditional Oral presentation:** Presentation for those interested in presenting to large groups with limited potential for interactions with attendees. Six-page paper maximum, 20 minute presentation with 10-minute question and answer session.
- **Poster Paper:** Presentation for those interested in direct interaction with individuals or small groups.

Student Paper Contest

As a part of the EMC symposium, graduate and undergraduate authors are eligible for the Symposium Best Student Paper contest. The student must be the primary author and should indicate that they wish to be considered for the contest when submitting the manuscript. Each student's professor will be asked to certify that the paper is primarily the work of the student.

Special Issue of IEEE Transactions on EMC

Authors of accepted papers will be invited to submit an extended version of their conference paper for possible inclusion in a special issue of the IEEE Transactions on Electromagnetic Compatibility featuring papers from the 2014 IEEE International Symposium on EMC including SIPI 2014. These submissions will be subjected to the same rigorous review as papers submitted for publication in regular issues of the IEEE Transactions on EMC.

Guidelines for Authors & Submittal Procedures

Prospective authors must submit electronically**.

- **A manuscript (4 – 6 pages) including all relevant results and conclusions.**
- **Choice of presentation format (traditional oral or open forum).**

** Manuscripts and Final papers are to be submitted through a website after November 1, 2013. Check back with the conference web site (<http://www.sipi2014.emc2014.org>) for updates on the paper submission process. During the electronic submission process a unique author code is created for tracking purposes. Submissions are reviewed anonymously so please do not include author names or affiliations on the Manuscript. Failure to comply with submission requirements may result in rejection.

Optional abstract submission

To increase the chance of paper acceptance, authors have an option to submit an abstract to <http://emc-center.org/OptionalAbstractSubmissionforSIPI2014.aspx>. (Note this site is different than the official paper submission site). Although final acceptance depends on the full manuscript, the technical committee will review the abstracts, provide an initial assessment of paper quality, and offer suggestions to improve the paper.

SIPI 2014 General Chair
Jun Fan (Jun.Fan@ieee.org)

SIPI 2014 Technical Program Co-Chairs
Dale Becker (wbecker@us.ibm.com)
Xiaoning Ye (xiaoning.ye@intel.com)

Steering Committee members:

Bruce Archambeault, *IBM*
Jim Nadolny, *Samtec*
Er-Ping Li, *A*STAR*
Michel Nakhla, *Carleton U*
Al Ruehli, *MST*
Sam Connor, *IBM*
Y. L. Li, *Intel*
Bill Samaras, *Intel*
Dan Jiao, *Purdue U.*

Todd Hubing, *Clemson U.*
Jim Drewniak, *MST*
Joung-ho Kim, *KAIST*
Jose Schutt-Aine, *UIUC*
Brice Achkir, *Cisco*
Anand Haridass, *IBM*
Dan Oh, *Altera*
Paul Franzon, *NCSU*
Zhiping Yang, *Apple*

Eric Bogatin, *BeTheSignal*
Flavio Canavero, *Politecnico di Torino*
Ruey-Beei Wu, *National Taiwan U.*
Antonio Orlandi, *U. of L'Aquila*
Tzong-Lin Wu, *National Taiwan U.*
Madhavan Swaminathan, *GIT*
Brian Young, *Freescale*
Christian Schuster, *Hamburg Tech. U.*